

SBR05M100BLP-p SBR05M60BLP-p

Part Number: **SBR DFN3030-4 Package**
Weight (mg): 16.2468

p = package designator
See Data Sheet

| Element | Material Group | Materials | CAS (if applicable) | Average mass homogeneous Material(%) | Percent of whole (%) | Mass (mg) | ppm Homogeneous Material | ppm overall |
|-------------------|------------------|--|---------------------|--------------------------------------|----------------------|-----------|--------------------------|-------------|
| Chip | Silicon w/Metal | Doped Silicon* | 7440-21-3 | 100.00% | 4.78 | 0.7763 | 1000000 | 47782 |
| Leadframe | C7025 | Cu | 7440-50-8 | 95.90% | 37.58 | 6.1056 | 959000 | 360395 |
| | | Si | 7440-21-3 | 0.73% | | | 7250 | 2725 |
| | | Ni | 7440-02-0 | 3.20% | | | 32000 | 12026 |
| | | Mg | 7439-95-4 | 0.18% | | | 1750 | 658 |
| Leadframe Plating | Internal plating | Ni | 7440-02-0 | 100.00% | 0.87 | 0.1412 | 1000000 | 8691 |
| | middle plating | Pd | 2023568 | 100.00% | 0.08 | 0.0128 | 1000000 | 788 |
| | outer plating | Au | 7440-57-5 | 100.00% | 0.02 | 0.0026 | 1000000 | 160 |
| Bond Wire | Gold Wire | Gold | 7440-57-5 | 100.00% | 1.75 | 0.2838 | 1000000 | 17468 |
| Encapsulation | EME-G770HCD | Silica fused | 60676-86-0 | 93.50% | 52.65 | 8.5535 | 935000 | 492252 |
| | | Epoxy resin | ----- | 3.00% | | | 30000 | 15794 |
| | | Phenol resin | ----- | 3.00% | | | 30000 | 15794 |
| | | Carbon Black | 1333-86-4 | 0.50% | | | 5000 | 2632 |
| Die Attach Epoxy | QMI519 | Ag | 7440-22-4 | 80.00% | 2.28 | 0.371 | 800000 | 18268 |
| | | palladium compound | ---- | 0.15% | | | 1500 | 34 |
| | | 2,6-Di-tert-butyl-p-cresol | 128-37-0 | 0.01% | | | 50 | 1 |
| | | Hydroquinone | 123-31-9 | 0.00% | | | 1 | 0 |
| | | Acrylate | ---- | 15.84% | | | 158449 | 3618 |
| | | Bismaleimide resin | ---- | 3.00% | | | 30000 | 685 |
| | | Polymer of polybutadiene and anlydride | ---- | 1.00% | | | 10000 | 228 |
| | | Total | | | | | | |

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, [Material Composition Declaration for Electronic Products](#).

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

- | | |
|--|--|
| Asbestos | Organic tin compounds |
| Antimony Compounds | Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.) |
| Azo compounds | Ozone Depleting Substances - Class II (HCFCs) |
| Cadmium and cadmium compounds | Perfluorooctane Sulphonate (PFOS) or related compounds |
| Certain Shortchain Chlorinated Paraffins | Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE |
| Chlorinated organic compounds | Polychlorinated Biphenyls (PCBs) |
| Dimethyl fumarate | Polychlorinated Naphthalenes (> 3 chlorine atoms) |
| Halogens | Radioactive Substances |
| Hexavalent chromium compounds | Red Phosphorus |
| Lead and lead compounds | Tributyl Tin (TBT) and Triphenyl Tin (TPT) |
| Mercury and mercury compounds | Tributyl Tin Oxide (TBTO) |

REACH SVHCs and other Substances of Concern:

- | | |
|---|---|
| Anthracene | 5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene) |
| 4,4'- Diaminodiphenylmethane | Bis (2-ethyl(hexyl)phthalate) (DEHP) |
| Dibutyl phthalate | Hexabromocyclododecane (HBCDD) |
| Cyclododecane | Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins) |
| Cobalt dichloride | Bis(tributyltin)oxide |
| Diarsenic pentaoxide | Lead hydrogen arsenate |
| Diarsenic trioxide | Triethyl arsenate |
| Sodium dichromate, dihydrate | Benzyl butyl phthalate |
| Beryllium, Beryllium Alloys and Compounds | Methylene Chloride |
| Hydrazine | Trichloroethene |
| Tetrachloroethylene | Methyl Ethyl Ketone |
| Toluene | Xylenes |
| Toluene Diisocyanate | |